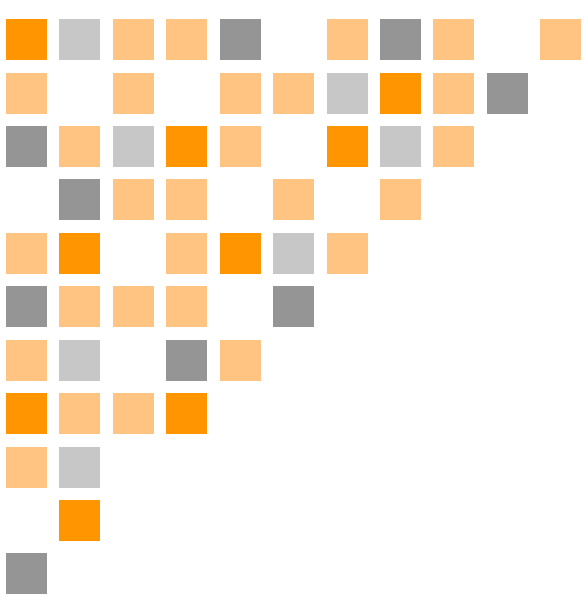




Quarterly Financial Result (Supplementary Materials)

Quarter 2: three months ended
June 30, 2026

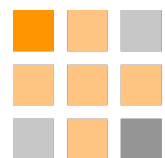
August12, 2026
Code: 6871

Disclaimer

- The contents of this presentation were compiled based on information readily available at the time of this presentation.
- Outlooks and other forward-looking statements are subject to change based on many uncertain worldwide factors including but not limited to market conditions, competition as well as semiconductor industry trends.
- Accordingly, please take note that the actual performance of the Company may vary considerably from the information and statements made in this presentation.

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Quarterly Financial Results (Q2)

Consolidated Result Summary

	FY12/2025	FY12/2026					
	Apr.-Jun.	Jan.-Mar.	Apr.-Jun.	QoQ		YoY	
	Q2 ①	Q1 ②	Q2 ③	(△) ③-②	(%)	(△) ③-①	(%)
Net Sales	18,996	20,945	28,261	+7,315	+34.9%	+9,264	+48.8%
Probe Card	18,536	20,629	27,912	+7,283	+35.3%	+9,376	+50.6%
TE ※	460	316	348	+32	+10.1%	(112)	(24.4%)
Gross Profit	8,787	9,898	15,217	+5,319	+53.7%	+6,430	+73.2%
Operating profit	4,711	5,647	9,909	+4,261	+75.4%	+5,197	+110.3%
Ordinary profit	4,492	5,991	10,268	+4,277	+71.4%	+5,776	+128.6%
Net Income Attributable to Owner of Parent	3,101	4,392	7,068	+2,675	+60.9%	+3,966	+127.9%

(Unit : Mils. of Yen)

*Amounts less than one million yen are rounded down

※ : Test Equipment

Consolidated Result Summary

(Unit : Mils. of Yen)

*Amounts less than one million yen are rounded down

	FY12/2025	FY12/2026					
	Jan.-Jun.		As of May.13		YoY		
	Previous year ①	Forecast ②	Results ③	(△) ③-②	(%)	(△) ③-①	(%)
Net Sales	33,120	45,700	49,206	+3,506	+7.7%	+16,086	+48.6%
Probe Card	32,199	45,000	48,542	+3,542	+7.9%	+16,342	+50.8%
TE ※	921	700	664	(35)	(5.1%)	(256)	(27.9%)
Gross Profit	16,401	—	25,115	—	—	+8,714	+53.1%
Operating profit	7,569	12,900	15,557	+2,657	+20.6%	+7,987	+105.5%
Ordinary profit	7,394	12,700	16,260	+3,560	+28.0%	+8,865	+119.9%
Net Income Attributable to Owner of Parent	4,774	9,200	11,461	+2,261	+24.6%	+6,686	+140.0%

※ : Test Equipment

Summary of Q2 FY2026 Results

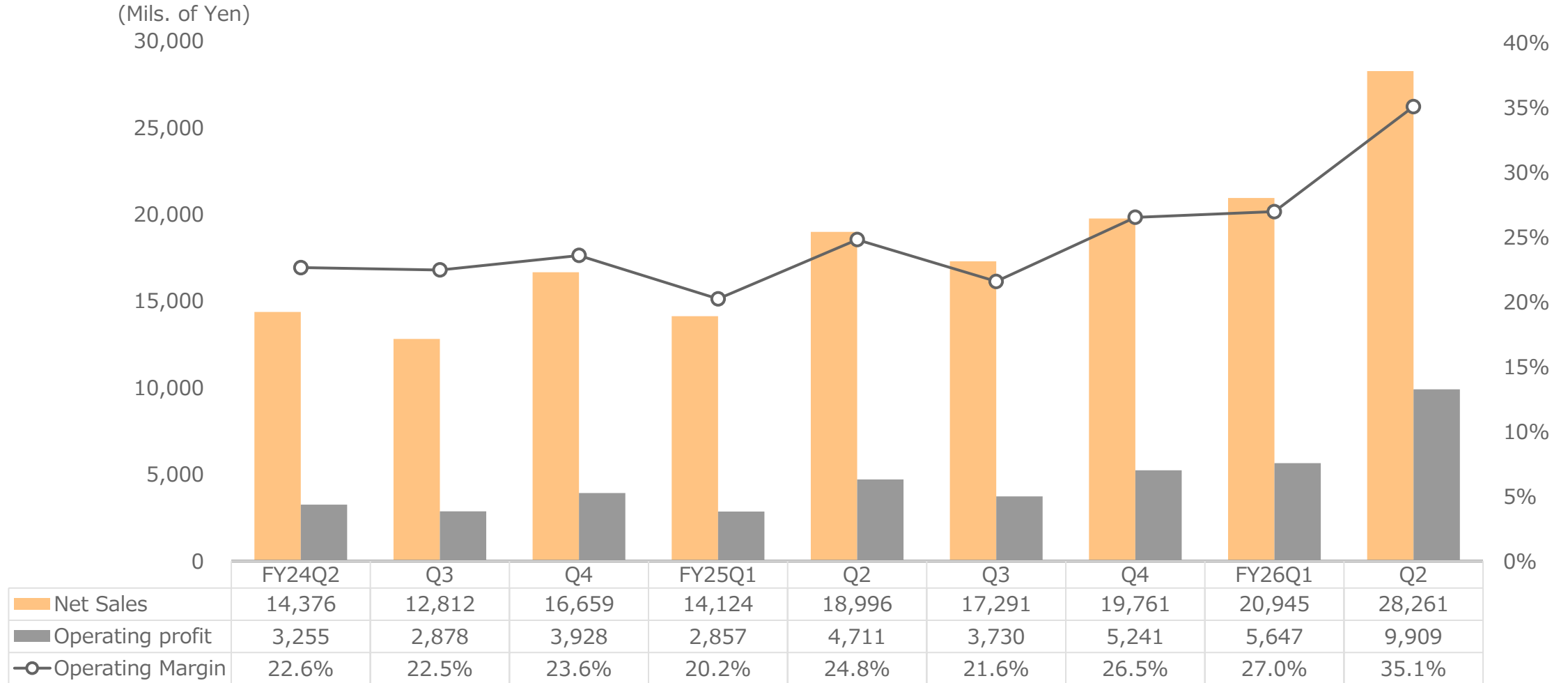
Probe card

- Sales of memory probe cards reached another record high, following the previous quarter, driven by production capacity expansion and shipments brought forward from the prior quarter.
- Sales of non-memory probe cards increased slightly quarter over quarter.
- Segment profit increased quarter over quarter, supported by contributions from high value-added products for DRAM applications.
- Order increased significantly quarter over quarter, with demand for DRAM applications, particularly HBM (High Bandwidth Memory), remaining strong.

TE

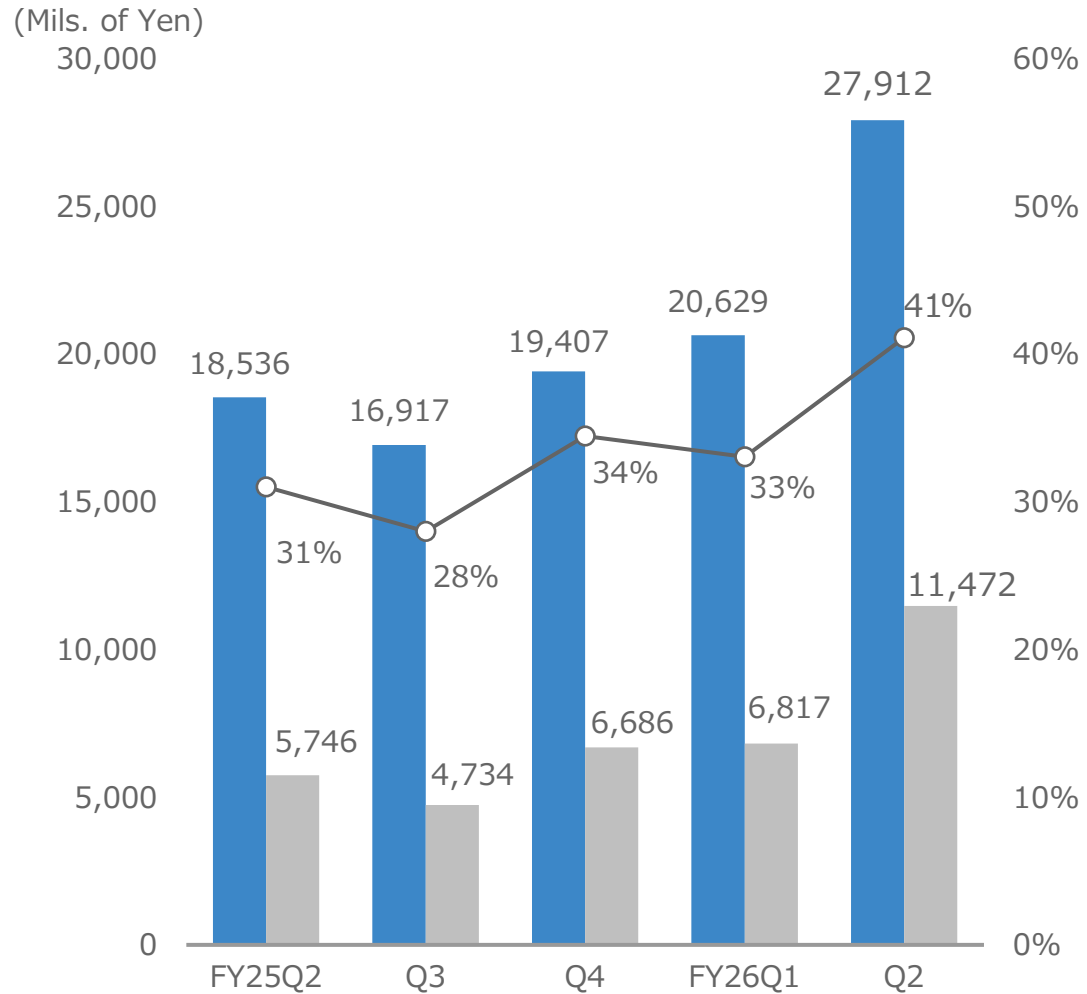
- Revenue increased quarter over quarter, reflecting solid demand for semiconductor test sockets.
- The segment recorded a loss.
- Customer evaluations are ongoing for Testalio semiconductor testers and Excelyze probe cards to secure new orders.

Quarterly Financial Result



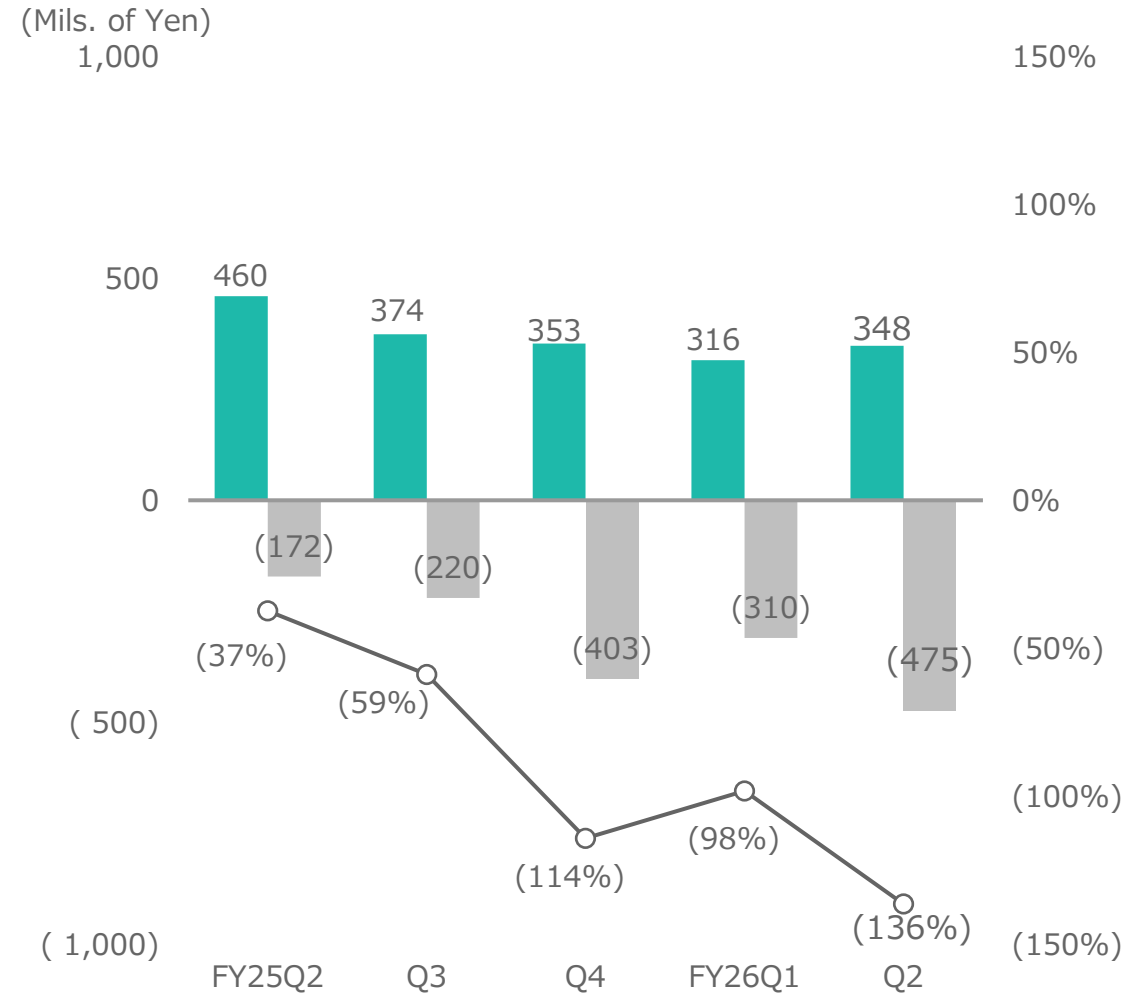
Business Condition by Segment

Probe card



■ Net Sales ■ Segment profit ○ Segment Margin

TE

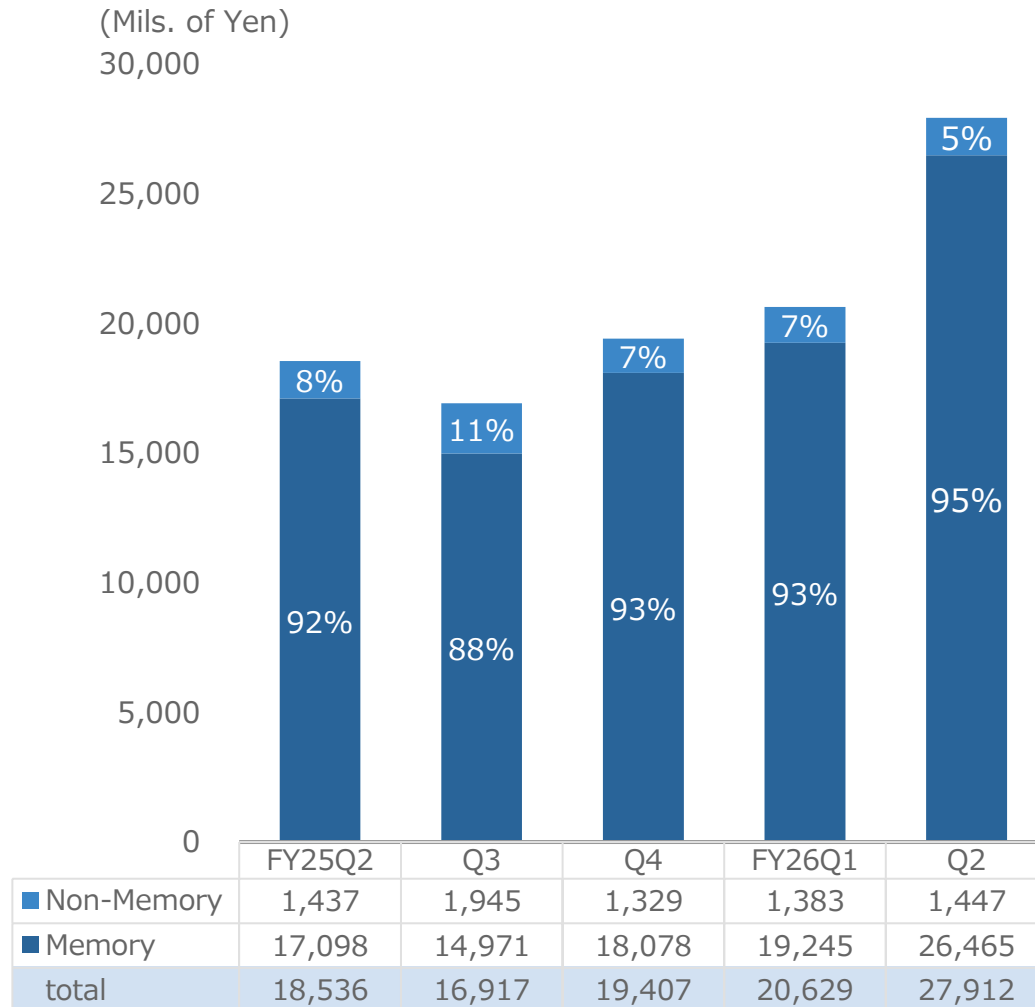


■ Net Sales ■ Segment profit ○ Segment Margin

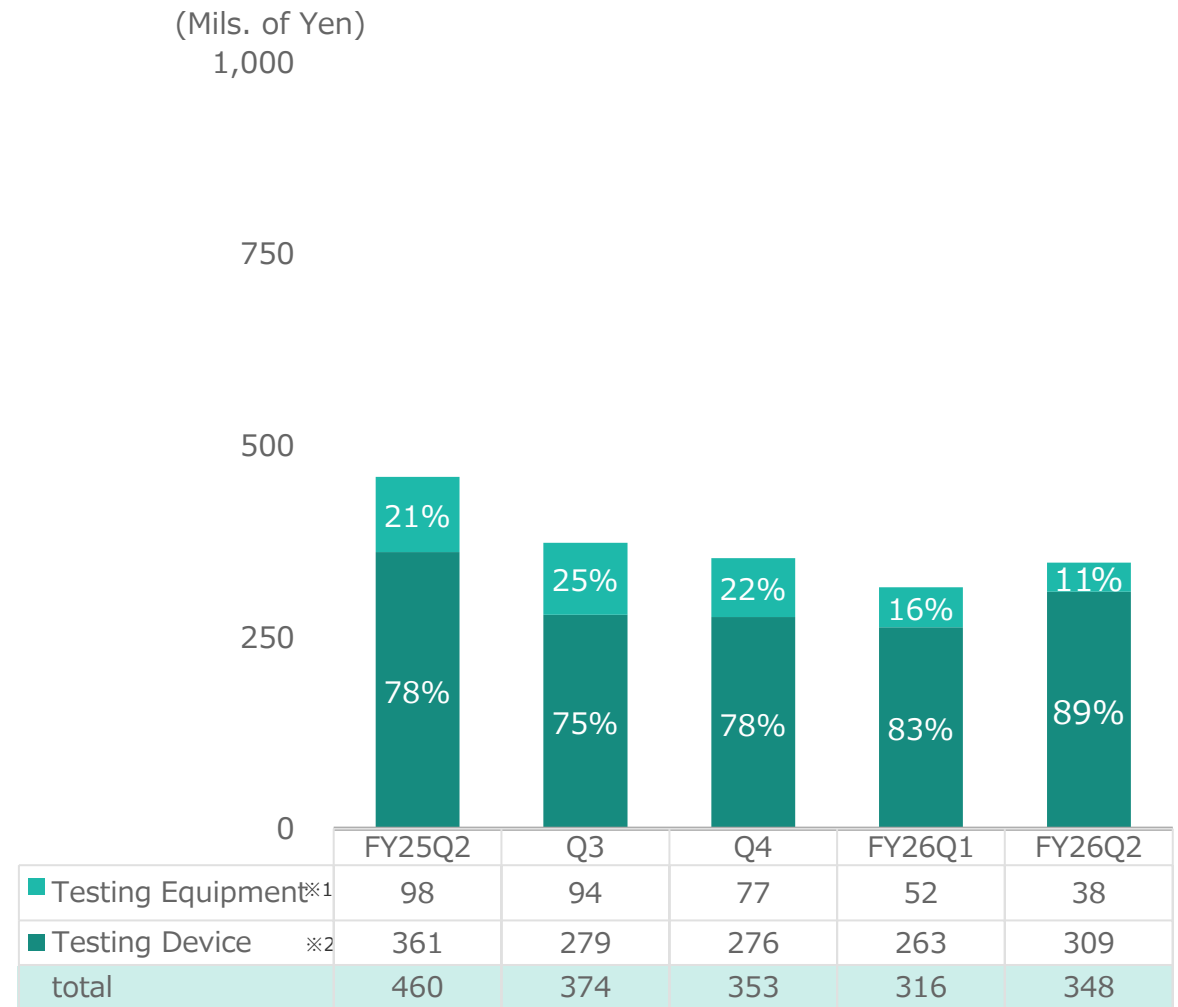
Quarterly Net Sales by Product

Probe card

TE



※ Including sales of Cantilever type



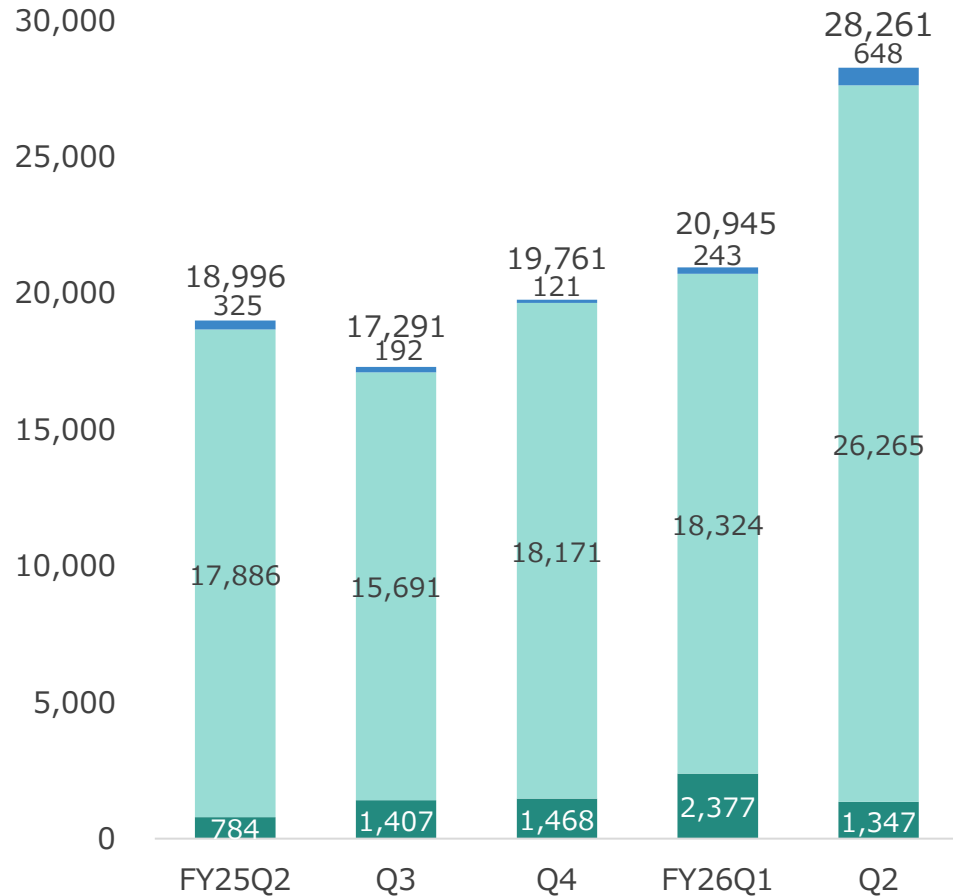
※1 Custom testers, Semiconductor probers, FPD test equipment, etc.

※2 Test sockets for semiconductors, Probe units for FPDs

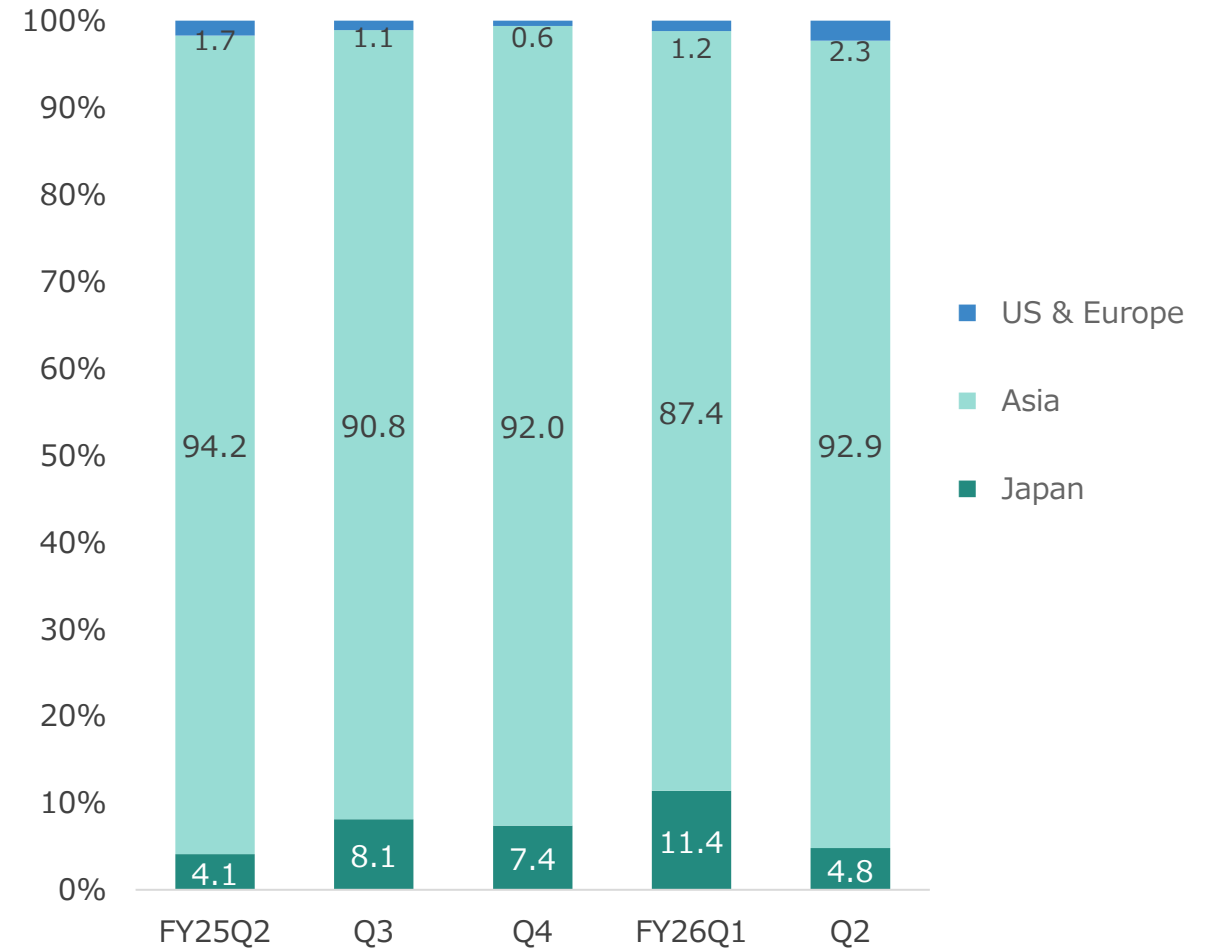
Quarterly Net Sales by Region

Net Sales

(Mils. of Yen)



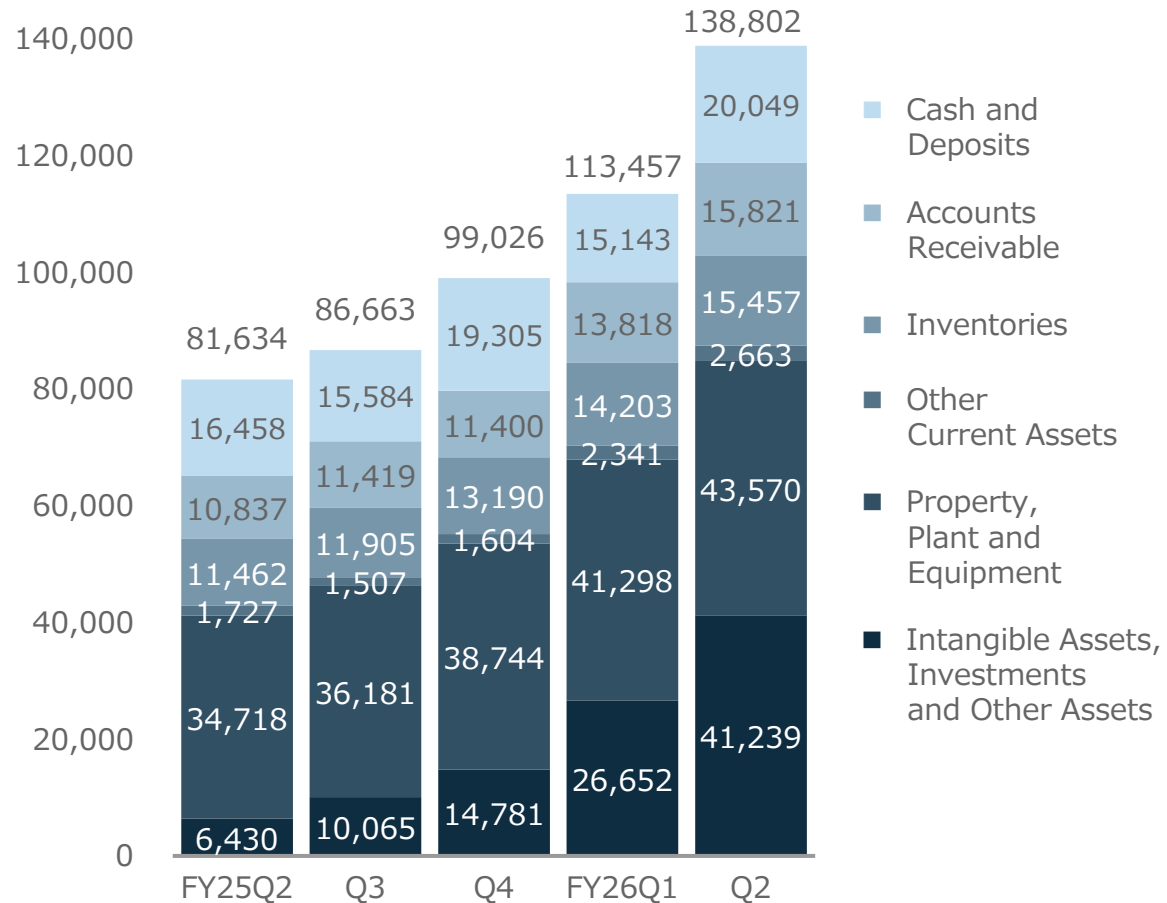
Percentage of sales



Consolidated Balance Sheet

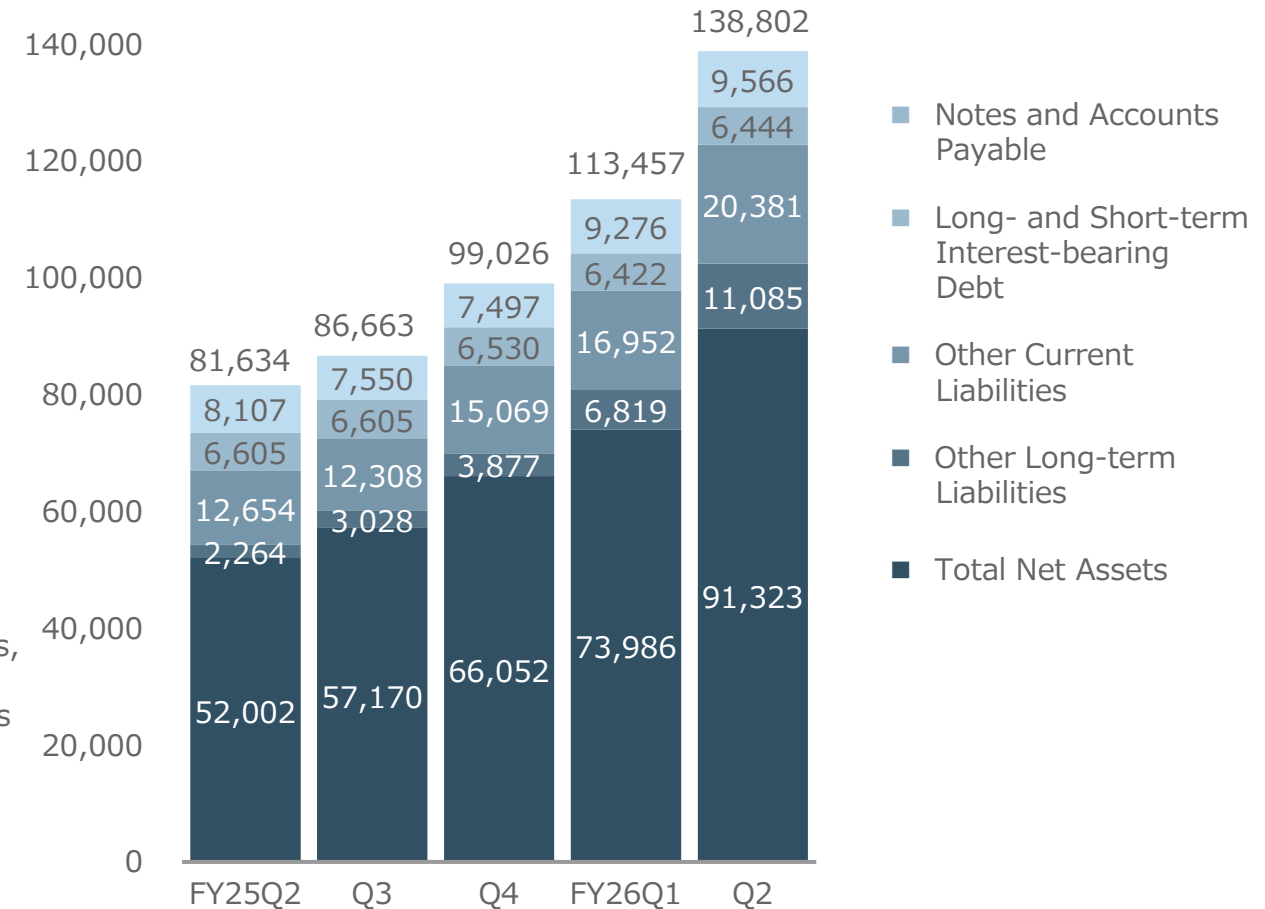
Assets

(Mils. of Yen)



Liabilities & Net Assets

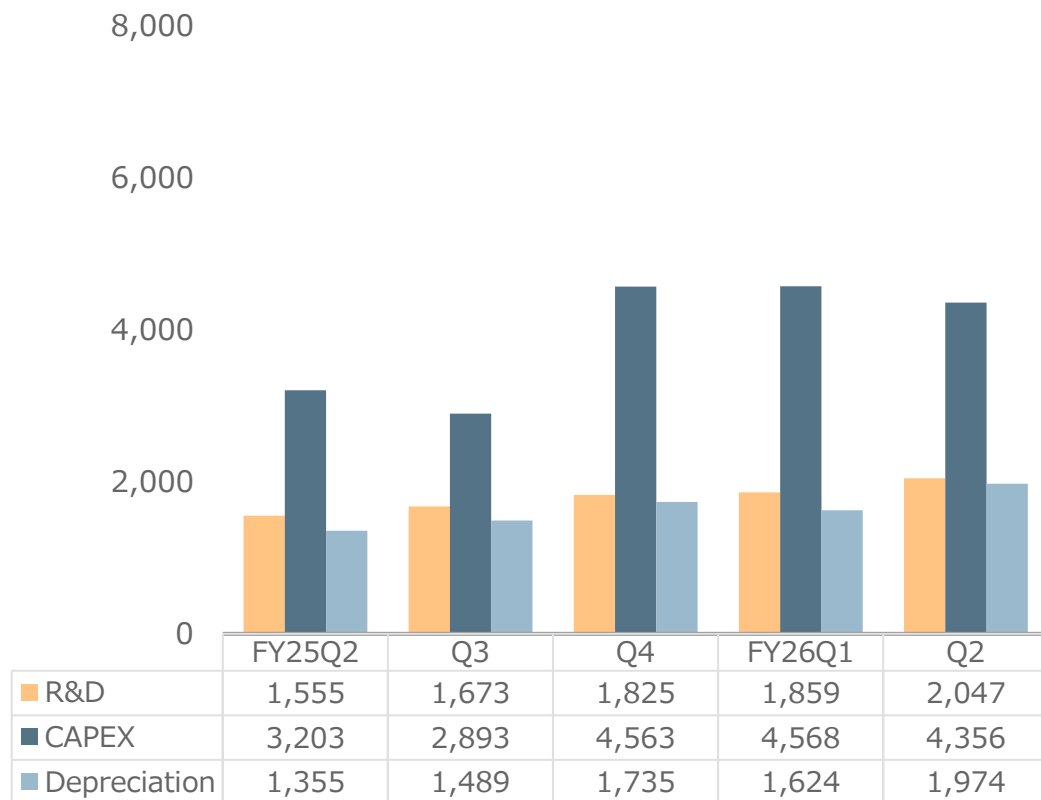
(Mils. of Yen)



Investments/Cash Flows

Investment, etc.

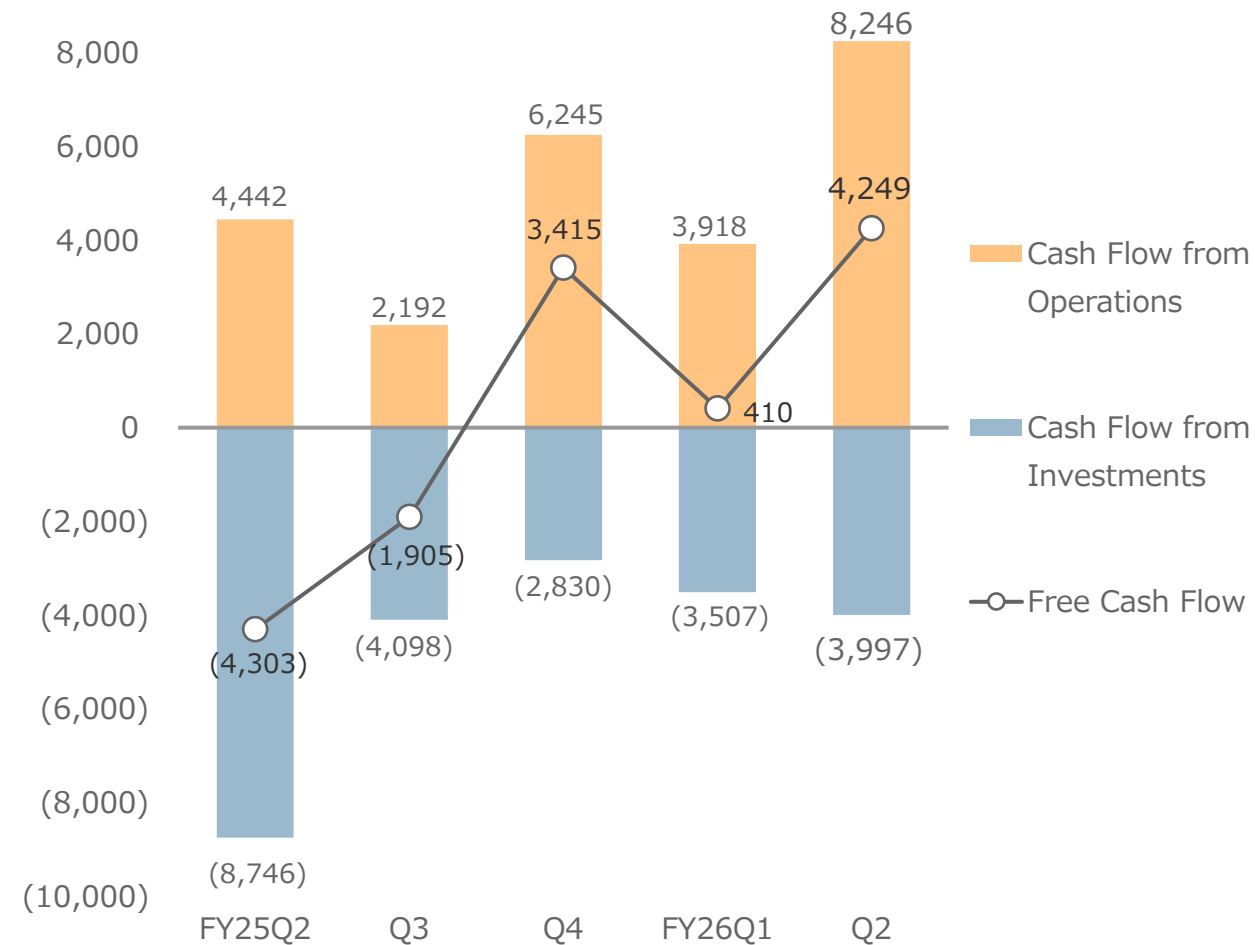
(Mils. of Yen)
10,000

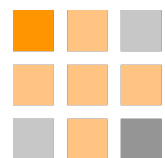


※ Including construction in progress

Cash Flows

(Mils. of Yen)
10,000





Forecasts

Financial Forecast

(Unit : Mils. of Yen)

*Amounts less than one million yen are rounded down

	FY12/2025	FY12/2026					
	Jan.-Sep. ①	As of May.13 (Jan.-Sep.) ②	Jan.-Sep. (New) ③	As of May.13		YoY	
				(△) ③-②	(%)	(△) ③-①	(%)
Net Sales	50,412	71,600	74,200	+2,600	+3.6%	+23,787	+47.2%
Probe Card	49,117	70,400	73,000	+2,600	+3.7%	+23,882	+48.6%
TE	1,295	1,200	1,100	(100)	(8.3%)	(195)	(15.1%)
Operating profit	11,300	21,900	22,400	+500	+2.3%	+11,099	+98.2%
Ordinary profit	11,273	21,400	23,100	+1,700	+7.9%	+11,826	+104.9%
Net Income Attributable to Owner of Parent	7,084	15,200	16,300	+1,100	+7.2%	+9,215	+130.1%

- FX rate assumption for FY12/2026: JPY 156.00 to USD, JPY 0.10 to KRW

Financial Forecast

(Unit : Mils. of Yen)
*Amounts less than one million yen are rounded down

	FY12/2025	FY12/2026		
	Jan.-Dec. (Previous year)	Jan.-Dec. (New)	YoY	
	①	②	(△) ②-①	(%)
Net Sales	70,173	103,800	+33,626	+47.9%
Probe Card	68,525	102,000	+33,474	+48.9%
TE	1,648	1,700	+51	+3.1%
Operating profit	16,542	31,400	+14,857	+89.8%
Ordinary profit	17,100	32,000	+14,899	+87.1%
Net Income Attributable to Owner of Parent	12,063	23,000	+10,936	+90.7%
Dividend (Yen)	95	178	+83	—

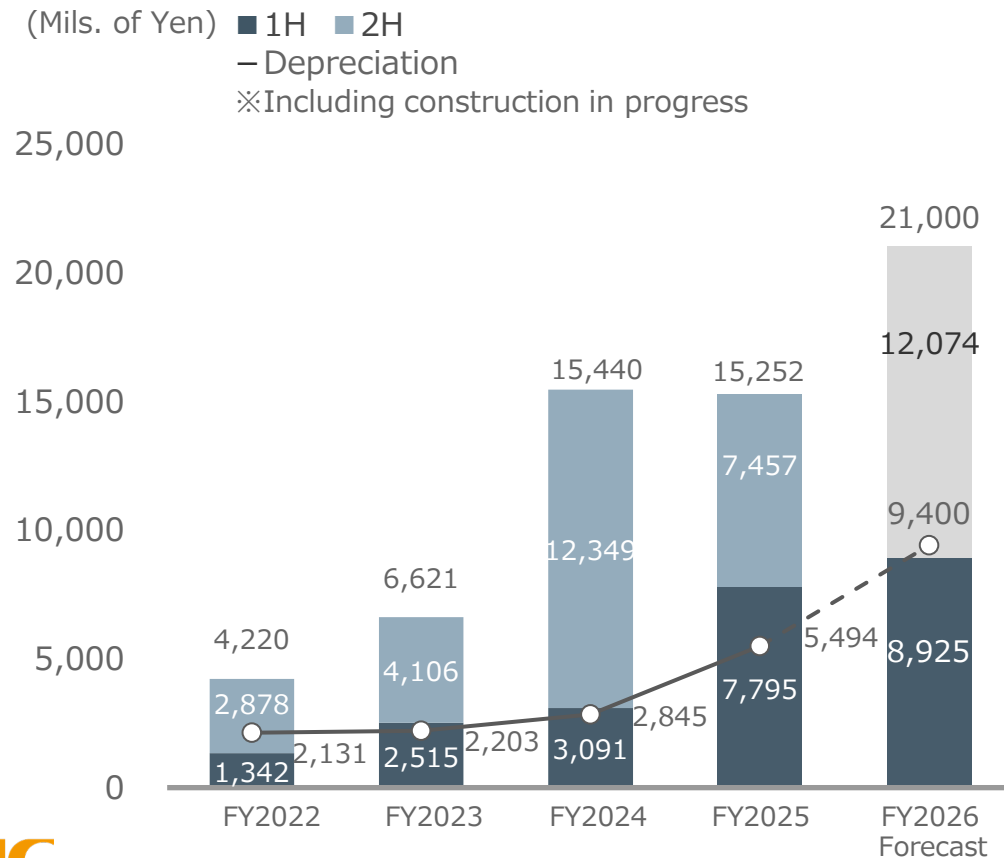
- FX rate assumption for FY12/2026: JPY 156.00 to USD, JPY 0.10 to KRW

Forecasts for R&D, Capex and Depreciation

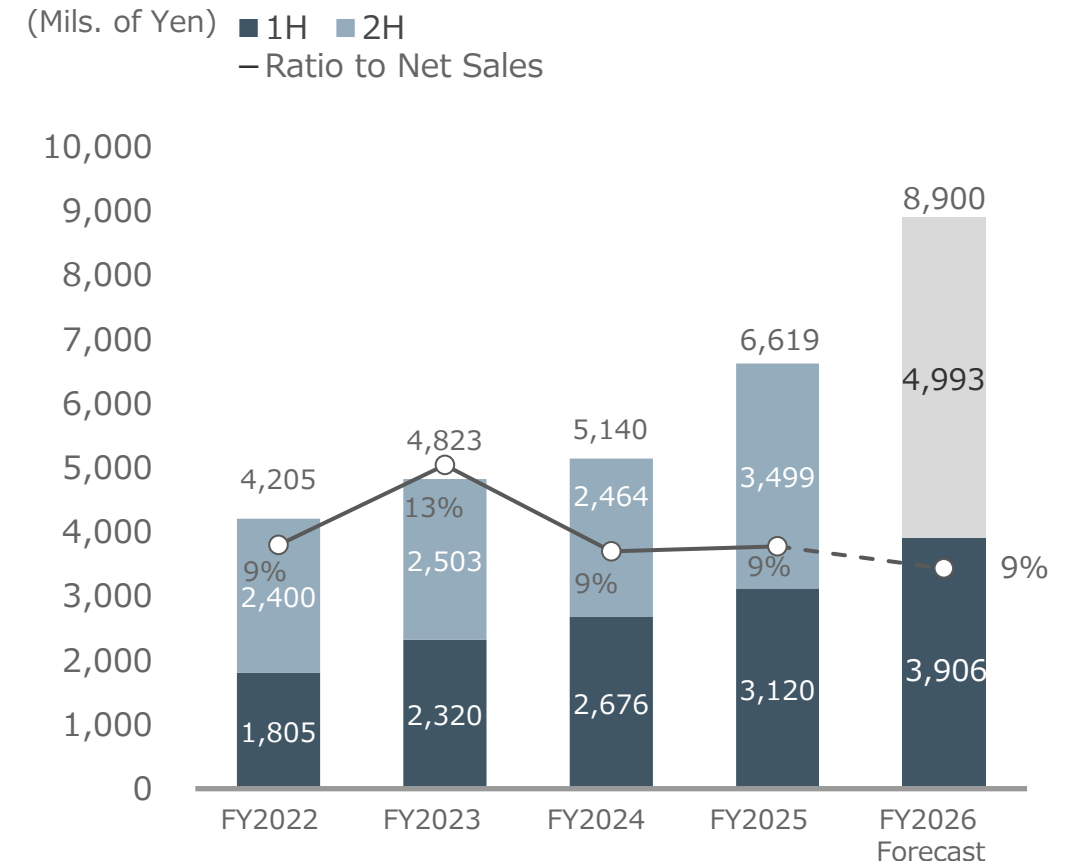
Accelerated production capacity expansion in response to strong memory probe card demand, while anticipating continued growth in the semiconductor market.

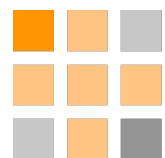
- Accelerating capital investments in production facilities for the new Aomori plant as much as possible.
- Accelerating the development of next-generation probe cards in anticipation of advances in semiconductor technologies.
- Promoting customer evaluations of Testalio and Excelyze to secure future orders

Capex & Depreciation



R&D





Glossary and Main Products

Glossary

Wafer: Circular crystalline silicon (Si) or gallium arsenide (GaAs) sliced into a thin disk substrate used for semiconductor electrical circuits.

Chip/Die: Dies and chips are small semiconductor devices. A semiconductor wafer is diced into many pieces, and each of these pieces is called a die or chip.

IC: Integrated circuit.

Memory IC: An integrated circuit made out of millions of capacitors and transistors that can store data such as DRAM, NAND Flash and etc.

Logic IC: An integrated circuit that performs logic functions.

DRAM: Dynamic random access memory.

A type of volatile memory with a wide range of uses including main storage for computers and general-purpose memory.

NAND-Type Flash Memory: A type of non-volatile memory that cannot be deleted even when the external power supply is interrupted. Used for USB memory, digital camera memory cards, mobile music players and mobile phone memory. Created by Toshiba in 1987.

LSI: Large-scale integrated circuit.

Called VLSI or ULSI when the transistor's degree of integration is increased.

Micro Computer: An IC that integrates memory and a microprocessor for arithmetic processing on one chip. Recently, the word "microcomputer" is often used to refer to those incorporated in home appliances or other products for electronic control.

System on Chip (SoC) / System LSI: Large-scale IC containing nearly an entire system on one chip. Combines multiple functions previously spread across multiple ICs onto one chip. Realizes small, high-performance machinery. Mainly used in processors and memory, input/output, interface and telecommunications circuitry.

Flip Chip: Flip chips have bump electrodes on the chip surface for the purpose of high-density surface mounting of IC chips on circuit boards. The bumps and wiring board terminals are connected with solder or conductive adhesive.

Bump: Bumps are solder bumps formed on IC pads. Bumps are normally formed with gold (Au) or solder and are used primarily in flip chips for connection to substrates.

Bonding Pad: Supply of power voltage to the chip and signal exchanges with exterior are normally conducted through the lead. The bonding pads are metal electrodes around the chip connecting this lead with each terminal on internal circuitry.

IoT: Internet of Things, allowing physical devices to be sensed or controlled remotely across existing internet infrastructure.

FPD: Flat panel display.

LCD: liquid crystal display.

Glossary

Wafer Test / Probe Test: An electrical test conducted by placing a probe needle on a wafer chip bonding pad.

Final Test / Package Test: Electrical testing of assembled ICs.

DUT: Device under test.

Area Array: A state which has test pads in a grid array on the surface of a chip.

Cantilever Probe Card: Also called a cantilever needle. A probe card using a one-sided needle probe as a fulcrum. Shaped by hand.

Advanced Probe Card: Probe cards other than the cantilever type.

Vertical Probe Cards: A vertical probe card is a probe card in which probe needles are vertical to the substrate. Vertical probe cards are suitable for area array, small pad, low voltage, low needle pressure, and high frequency measurement.

MEMS: Micro-Electro-Mechanical Systems.

MEMS Type Probe Card: MEMS type probe cards are probe cards using MEMS technology. They have a structure that allows the mechanical movement of probe terminals.

DFT: Design for testability

BIST: Built In Self Test

AI(Artificial Intelligence): The simulation of human intelligence processes by machines. It generally needs various type of semiconductors like image sensors.

Generative AI: automatically creates diverse content, including images, videos, and text. It learns from extensive pre-analyzed data, enabling the generation of new content. High-performance semiconductors like GPUs or HBMs are crucial for effective generative AI.

GPU (Graphics Processing Unit):A semiconductor chip that handles complex data calculations, including 3D graphics processing. It excels in parallel computing. When combined with HBM, it enables even faster performance, especially for generative AI.

HBM (High Bandwidth Memory) : A type of DRAM known for its wide bandwidth and high-power efficiency. By stacking DRAM chips and connecting them to a processor using multiple buses, it achieves fast and large-capacity data transfer. It is primarily packaged with GPUs/CPU and used in HPCs and AI servers.

HPC(High Performance Computing) : A technology that performs complex computational processing on massive data at high speeds. It uses high-performance processors to handle big data efficiently.

General-purpose server : A computer or program that performs necessary processing through a network in response to requests from users.

AI server: A specialized server designed specifically for training and inference of generative AI. It is equipped with powerful CPUs, GPUs, HBM, and other devices, providing higher computational capabilities, large memory storage, high bandwidth, and low latency.

Data center :A facility designed to securely store servers and network equipment. When investments in data centers increase, there is often a higher demand for general-purpose servers, which in turn can lead to an increased need for DRAM chips.

Our Products

Probe Cards

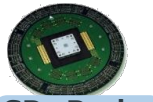
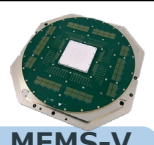
U-Probe: Our core product, realizing the world's first wafer-scale probing created with MJC's proprietary MEMS probe "micro-cantilever" and global top-level thin-film multilayer technology. With a bare minimum of contacting times via a crescent arrangement for DRAM, this product is currently the industry standard. Mainly used for memory testing on DRAM and flash memory.

SP-Probe: Vertical spring pin-type probe card suitable for 12-inch wafer batch measurements. Mainly used for testing NAND flash memory.

MEMS-V / Vertical-Probe: Vertical needle-type probe card used for testing highly integrated, high-speed multi-pin logic devices. Provides flexible support for a variety of pad and fine pitch arrangements and is suitable for multiple individual simultaneous measurements during testing of SoC and other advanced logic devices.

MEMS-SP: Probe card used for MEMS probe developed for testing SoC devices and other flip chip-type logic devices.

Main Applications for MJC Probe Card Products

	Memory		Logic	
	DRAM	Flash	SoC	
Vertical		 SP-Probe	 Vertical-Probe	 SP-Probe
MEMS Type	 U-Probe		 MEMS-V	 MEMS-SP

Our Products

Test Equipment

Semiconductor Tester: A system that gives electrical signals to a semiconductor device to compare output signals with expected values.

Wafer Prober: A system that handles the wafer to make contact in the designated position on the device.

Test Socket: In the final inspection of semiconductor manufacturing, a fixture is used to electrically connect the packaged device and tester. There are two types: 'J-Contacts,' suitable for high-frequency and high-performance devices, and 'BeeContacts,' which have a unique spring probe structure with excellent contact stability.

RF Probe: RF Probe for High-frequency Measurement, Such as Radio Frequency and Microwave Signals.

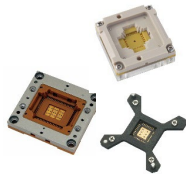
Probe Unit: Probe card with a built-in LCD prober. This blade-type unit developed by MJC is an industry standard.



Semiconductor
Tester



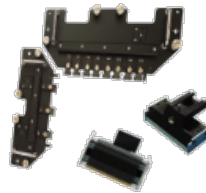
Wafer Prober



Test Socket



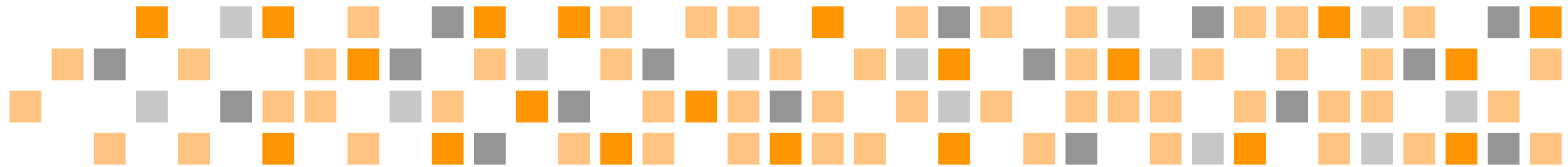
RF Probe



Probe Unit



MJC YOUR Best Partner, MJC Anytime Anywhere



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